



## Material Content Data Sheet



<b>Sales Product Name</b>		SPU04N60C3		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001077938						
<b>Package</b>		PG-TO251-3-341		<b>Weight*</b>		382.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.279	0.86	0.86	8576	8576
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		180	
	non noble metal	iron	7439-89-6	0.229	0.06		600	
	non noble metal	copper	7440-50-8	228.946	59.88	59.96	598845	599625
	non noble metal	aluminium	7429-90-5	0.446	0.12	0.12	1168	1168
wire	inorganic material	antimonytrioxide	1309-64-4	1.721	0.45		4502	
encapsulation	plastics	brominated resin	-	1.844	0.48		4823	
	organic material	carbon black	1333-86-4	1.967	0.51		5145	
	plastics	epoxy resin	-	16.596	4.34		43409	
	inorganic material	silicondioxide	60676-86-0	100.803	26.37	32.15	263667	321546
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9783	9783
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1331	1331
solder	non noble metal	tin	7440-31-5	0.059	0.02		155	
	noble metal	silver	7440-22-4	0.074	0.02		194	
	non noble metal	lead	7439-92-1	2.827	0.74	0.78	7395	7744
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	5.02	5.02	50162	50227
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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